L Number	Hits	Search Text	DB	Time stamp
1	298253	mask	USPAT;	2002/04/18
*	230233	mas n	EPO; JPO;	17:32
,			DERWENT	
2	10145	conformable	USPAT;	2002/04/18
-			EPO; JPO;	17:32
			DERWENT	[
3	1646757	substrate workpiece wafer	USPAT;	2002/04/18
			EPO; JPO;	17:33
			DERWENT	1
4	613481	deform\$5	USPAT;	2002/04/18
Ì			EPO; JPO;	17:34
_			DERWENT	2002/04/10
5	621248	conformable deform\$5	USPAT;	2002/04/18
}			EPO; JPO; DERWENT	17:34
	8338	mask and (substrate workpiece wafer) and	USPAT;	2002/04/18
6	0330	(conformable deform\$5)	EPO; JPO;	17:34
		(Conformable deloimas)	DERWENT	17.31
7	48327	electroplat\$3	USPAT;	2002/04/18
'	1002,	01001207140	EPO; JPO;	17:34
			DERWENT	
8	3295	electrolytic adj deposition	USPAT;	2002/04/18
			EPO; JPO;	17:34
			DERWENT	
9	746	electrolytically adj depositing	USPAT;	2002/04/18
	[EPO; JPO;	17:35
			DERWENT	
10	116	electrolytically adj deposit	USPAT;	2002/04/18
	-		EPO; JPO;	17:35
	22711		DERWENT	2002/04/18
. 11	23714	electrodeposition	USPAT;	17:35
			EPO; JPO; DERWENT	17.33
12	70237	electroplat\$3 (electrolytic adj	USPAT;	2002/04/18
12	70237	deposition) (electrolytically adj	EPO; JPO;	17:35
]	depositing) (electrolytically adj	DERWENT	- / 100
	1	deposit) electrodeposition		
13	1049		USPAT;	2002/04/18
		deposition) (electrolytically adj	EPO; JPO;	17:36
	-	depositing) (electrolytically adj	DERWENT	
		deposit) electrodeposition) and (mask and		
		(substrate workpiece wafer) and		
	<u>.</u>	(conformable deform\$5))		0000/04/10
14	118105	mask same (substrate workpiece wafer)	USPAT;	2002/04/18
			EPO; JPO; DERWENT	17:36
15	662	(mask same (substrate workpiece wafer))	USPAT;	2002/04/18
15	662	and (conformable deform\$5) and	EPO; JPO;	17:52
		(electroplat\$3 (electrolytic adj	DERWENT	
		deposition) (electrolytically adj		
		depositing) (electrolytically adj		
		deposit) electrodeposition)		
16	119319		USPAT;	2002/04/18
1			EPO; JPO;	17:53
			DERWENT	
17	54		USPAT;	2002/04/18
		workpiece wafer)) and (conformable	EPO; JPO;	18:08
İ		deform\$5) and (electroplat\$3	DERWENT	
		(electrolytic adj deposition)		
		(electrolytically adj depositing)		
1		(electrolytically adj deposit)		
18	32612	electrodeposition)) 205/\$.ccls.	USPAT;	2002/04/18
10	32012	20074.0013.	EPO; JPO;	18:08
			DERWENT	20.00
L	L	<u> </u>	1	1

19	34	205/\$.ccls. and ((mask same (substrate	USPAT;	2002/04/18
		workpiece wafer)) and (conformable	EPO; JPO;	18:08
		deform\$5) and (electroplat\$3	DERWENT	
		(electrolytic adj deposition)		
		(electrolytically adj depositing)		
		(electrolytically adj deposit)		
[electrodeposition))		